

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSC0901NSI	**Issued**	17. April 2021
MA#	MA005421428		
Package	PG-TDSON-8-51	**Weight***	101.82 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.671	0.66	0.66	6590	6590
leadframe	inorganic material	phosphorus	7723-14-0	0.014	0.01		134	
	non noble metal	zinc	7440-66-6	0.055	0.05		535	
	non noble metal	iron	7439-89-6	1.090	1.07		10708	
	non noble metal	copper	7440-50-8	44.271	43.49	44.62	434785	446162
wire	noble metal	gold	7440-57-5	0.030	0.03	0.03	293	293
encapsulation	organic material	carbon black	1333-86-4	0.088	0.09		864	
	plastics	epoxy resin	-	4.045	3.97		39730	
	inorganic material	silicondioxide	60676-86-0	39.839	39.13	43.19	391255	431849
leadfinish	non noble metal	tin	7440-31-5	1.264	1.24	1.24	12411	12411
plating	noble metal	silver	7440-22-4	0.029	0.03	0.03	285	285
solder	noble metal	silver	7440-22-4	0.023	0.02		230	
	non noble metal	tin	7440-31-5	0.047	0.05		459	
	non noble metal	lead	7439-92-1	0.865	0.85	0.92	8499	9188
heat sink clip	inorganic material	phosphorus	7723-14-0	0.003			28	
	non noble metal	zinc	7440-66-6	0.011	0.01		112	
	non noble metal	iron	7439-89-6	0.228	0.22		2237	
	non noble metal	copper	7440-50-8	9.250	9.08	9.31	90845	93222
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com